SEAGATE

Seagate® Nytro® 1351, 1551 SSD

Product Manual

Nytro 1351 - Read Intensive Models	**Nytro 1551 - Mixed Workload Models**
SED - TCG Enterprise	**SED - TCG Enterprise**
XA240LE10023	XA240ME10023
XA480LE10083	XA480ME10083
XA960LE10083	XA960ME10083
XA1920LE10083	XA1920ME10083
XA3840LE10083	XA3840ME10083
SED - TCG Opal	**SED - TCG Opal**
XA240LE10043	XA240ME10043
XA480LE10103	XA480ME10103
XA960LE10103	XA960ME10103
XA1920LE10103	XA1920ME10103
XA3840LE10103	XA3840ME10103
Standard	**Standard**
XA240LE10003	XA240ME10003
XA480LE10063	XA480ME10063
XA960LE10063	XA960ME10063
XA1920LE10063	XA1920ME10063
XA3840LE10063	XA3840ME10063

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Revision History

Version and Date	Description of Changes
Rev A, July 2018	First release of the document.

Contents

Seagate Technology Support Services

For Nytro® Support, visit: http://www.seagate.com/support/by-product/ssd-and-pcie-flash/

For information regarding online support and services, visit: http://www.seagate.com/contacts/

Available services include:

- Presales & Technical support
- Global Support Services telephone numbers & business hours
- Authorized Service Centers

For information regarding Warranty Support, visit: http://www.seagate.com/support/warranty-and-replacements/

1. Introduction

The Seagate® Nytro® 1351 and Nytro 1551 are next generation enterprise SATA SSDs that deliver enterprise class features in a 2.5-inch × 7 mm form factor.

Table 1   Features

Feature	Description
Capacity	■ 240, 480, 960, 1920, or 3840 GB
Certifications, Eco-Compliance	■ CE, UL, cUL, RCM, BSMI, KCC, TUV, Microsoft WHCK, Microsoft WHQL, SATA-IO ■ RoHS, WEEE
Dimension	■ Width: 69.85±0.25 millimeters ■ Length: 100±0.25 millimeters ■ Height: Maximum 7 millimeters
Endurance	■ Lifetime Endurance: 1 or 3 DWPD depending on the model
Logical Block Size	■ 512 bytes
Form Factor	■ 2.5 inch × 7 mm Standard SSD
Interface Compliance	■ Fully compliant with SATA revision 3.2 and 3.3, compatible with SATA 6.0Gb/s and 3.0Gb/s interface rates. ■ Fully compliant with ATA/ATAPI Command Set – 4 and supports all mandatory ATA commands defined in the ATA8-ACS specification. — ATA General Feature Command Set — Power Management Command Set — Security Mode Feature Set — SMART Command Set — Device Statistics — SMART Command Transport — Dataset Management Command Set — Host Protected Area Command Set — 48-bit Address Command Set — General Purpose Log Command Set — Native Command Queuing — Software Settings Prevention — ATA Sanitize Command Set — Identify Device Command Set — Log Addresses Requirement ■ PIO, DMA, UDMA (up to 6, dependent on host) supported. ■ SATA 6.0Gb/s Native Command Queuing (NCQ): up to 32 commands. ■ SMART command transport (SCT) technology. ■ Data Set Management Command Trim support.
NAND	■ 3D eTLC
Flash Controller	■ Seagate proprietary Flash Controller ■ Seagate DuraWrite™ Technology for improved performance
Performance	■ See Section 2.2, *Performance, on page 10*.
Power Consumption	■ See Section 2.3, *Power, on page 12*.

Table 1   Features (Continued)

Feature	Description
Power Loss Data Protection	■ In-process writes to the NAND are completed in the event of an unexpected power loss
Power Management	■ OS-aware hot-plug/hot-swap support
Power On Ready	■ See Section 2.3, *Power, on page 12*.

Reliability	■ Power-loss data protection
	■ SMART thermal monitoring
	■ MTBF: 2 million hours @ 55 C
	■ UBER: 1 read error per 10^{17} bits read
	■ End-to-End data-path protection
	■ Seagate SHIELD – Advanced ECC for improved reliability with minimal impact on performance
	  — Adaptive Code Rates
	  — Intelligent Noise handling
	  — Adaptive Read Voltage calibration
	  — Multi-Level Error Correction - Best-in-class LDPC implementation
	■ Seagate RAISE (Redundant Array of Independent Silicon Elements)
	  — Protects user data from various flash silicon failures
	  — RAID-like data protection and recovery from flash memory failures
	  — Operates within a single drive without impacting performance
	  — Corrects a single page, single block or single die failure within one RAISE stripe on capacities 480GB and higher. For 240GB, corrects a single page, single block or single plane failure within one RAISE stripe.

Security	■ Seagate Secure™
	■ Secure Supply Chain
	  — O-TTPS (Open Trusted Technology Provider Standard) compliant
	■ SD&D (Secure Download & Diagnostics)
	  — Cryptographic FW signing, RSA 2048 key
	  — Secure Boot
	  — Locked Diagnostic Port
	  — FW Authenticity and Integrity Verification, SHA 256
	■ Instant Secure Erase
	■ TCG Enterprise Protocol, AES-256 Encryption models
	■ TCG Opal Protocol, AES-256 Encryption models

Shock	■ Operating: 1000G, duration 0.5ms ■ Non-Operating: 1000G, duration 0.5ms
Vibration	■ Operating: Random, 3.8 Grms, 10-3000Hz, Uniform PSD:0.005 G^2/Hz ■ Non-Operating: Random, 7 Grms, 10-500Hz, Uniform PSD:0.01 G^2/Hz
Voltage	■ 5 V (240GB, 480GB) ■ 5 V and 12 V (960GB, 1920GB, 3840GB)
Data Retention	■ 3 months power-off retention at 40 C once the drive reaches the rated write endurance (EOL)
Temperature Range	■ Operating: 0°C to 70°C ■ Non-operating: -40°C to 85°C
Thermal gradient	■ Operating: 20°C/hour ■ Non-operating: 30°C/hour

Table 1   Features (Continued)

Feature	Description
Tunable Capacity	■ Set to Capacity Optimized or Performance Optimized
TBW	■ Up to 21000 TBW.
Warranty	■ Five years limited Warranty with Media Usage, based on the shorter of term or endurance usage of the drive. See Section 2.7, *Endurance, on page 15*.
Weight	■ up to 77g ±5%

2. Specifications

2.1   Models and Capacity

Table 2   Nytro 1351 - Read Intensive - 1 DWPD Models

Capacity (GB)	LBA Count	SED - TCG Enterprise	SED - TCG Opal	Standard
240	46,88,62,128	XA240LE10023	XA240LE10043	XA240LE10003
480	93,77,03,088	XA480LE10083	XA480LE10103	XA480LE10063
960	1,87,53,85,008	XA960LE10083	XA960LE10103	XA960LE10063
1920	3,75,07,48,848	XA1920LE10083	XA1920LE10103	XA1920LE10063
3840	7,50,14,76,528	XA3840LE10083	XA3840LE10103	XA3840LE10063

Table 3   Nytro1551 - Mixed Workload - 3 DWPD Models

Capacity (GB)	LBA Count	SED - TCG Enterprise	SED - TCG Opal	Standard
240	46,88,62,128	XA240ME10023	XA240ME10043	XA240ME10003
480	93,77,03,088	XA480ME10083	XA480ME10103	XA480ME10063
960	1,87,53,85,008	XA960ME10083	XA960ME10103	XA960ME10063
1920	3,75,07,48,848	XA1920ME10083	XA1920ME10103	XA1920ME10063
3840	7,50,14,76,528	XA3840ME10083	XA3840ME10103	XA3840ME10063

2.2   Performance

Table 4   Performance - Capacity Optimized (7% OP)

Capacity	Units	240 GB		480 GB		960 GB		1920 GB		3840 GB	
Compressibility	**%**	**0%**	**20%**	**0%**	**20%**	**0%**	**20%**	**0%**	**20%**	**0%**	**20%**
128K SR QD32	MB/s	560	560	560	560	560	560	560	560	560	560
128K SW QD32	MB/s	240	345	465	535	535	535	535	535	535	535
4K RR QD32	KIOPs	55	55	75	75	90	90	90	90	85	85
4K R70R QD32	KIOPs	20	30	25	40	35	50	45	65	45	60
4K RW QD32	KIOPs	12	30	15	50	20	55	20	50	20	45
8K RR QD32	KIOPs	45	45	55	55	55	55	55	55	55	55
8K R70R QD32	KIOPs	12	25	15	30	20	35	30	45	30	45
8K RW QD32	KIOPs	6	20	8	30	13	40	14	40	12	40
4K RR Latency QD1	usec	155	155	155	155	155	155	160	160	175	175
4K RW Latency QD1	usec	80	40	65	40	60	40	60	35	60	40
4K RR QD32 99% CI	usec	1700	1580	760	720	580	600	570	560	730	700
4K R70R QD32 99% CI	usec	6160	4500	4980	3620	3900	3020	3650	2710	3470	2610
4K RW QD32 99% CI	usec	4980	2920	3720	1630	2940	800	2880	1830	2950	1960
4K RR QD32 99.99% CI	usec	2000	2000	1720	1440	800	950	850	860	1850	1780
4K R70R QD32 99.99% CI	usec	12450	8620	9420	7450	7770	6330	6710	5290	5970	5550
4K RW QD32 99.99% CI	usec	7440	5580	5740	2990	4360	2090	3650	2000	3830	2110

NOTE   Information on performance:

- MB is 10^6. MB/s = 10^6 bytes/sec.

- 4 KB = 4,096 bytes, 8 KB = 8,192 bytes.

- All workloads set to 4 KB alignment.

- Data compressibility values of 0% and 20% as set with VDBench.

- All metrics represent sustained values, across full LBA range.

- Performance measured with queue depth set to 32.

- Drive write cache enabled. Due to the PLDP feature, the SSD always behaves as if WCE is enabled.

- Performance test precondition: Drive is preconditioned with 2x drive capacity 128 KB write IOs.

- Results obtained with a direct SATA port connection to host. Results may vary with system configuration.

Table 5   Performance - Performance Optimized (28% OP)

Capacity	Units	200 GB		400 GB		800 GB		1600 GB		3200 GB	
Compressibility	%	0%	20%	0%	20%	0%	20%	0%	20%	0%	20%
128K SR QD32	MB/s	560	560	560	560	560	560	560	560	560	560
128K SW QD32	MB/s	240	345	465	535	535	535	535	535	535	535
4K RR QD32	KIOPs	55	55	80	80	90	90	90	90	90	90
4K R70R QD32	KIOPs	25	30	35	45	45	55	55	70	55	70
4K RW QD32	KIOPs	20	30	30	65	45	65	45	65	35	60
8K RR QD32	KIOPs	45	45	55	55	55	55	55	55	55	55
8K R70R QD32	KIOPs	20	25	25	35	35	40	40	45	35	45
8K RW QD32	KIOPs	12	20	15	40	30	45	30	45	20	35
4K RR Latency QD1	usec	155	155	155	150	145	140	145	140	155	150
4K RW Latency QD1	usec	45	40	45	40	45	40	45	40	55	40
4K RR QD32 99% CI	usec	1490	1580	690	670	500	550	500	500	610	580
4K R70R QD32 99% CI	usec	4900	4500	3950	3480	3500	2860	2970	2420	3060	2140
4K RW QD32 99% CI	usec	3870	2920	2970	1590	1560	700	1130	690	1970	810
4K RR QD32 99.99% CI	usec	2000	2000	1210	-	-	870	800	790	1030	980
4K R70R QD32 99.99% CI	usec	9140	8620	8280	7640	6800	5700	5750	4990	5840	4950
4K RW QD32 99.99% CI	usec	5990	5580	5580	-	3330	1810	2670	1500	2870	2000

NOTE   Information on performance:

- MB is 10^6. MB/s = 10^6 bytes/sec.

- 4 KB = 4,096 bytes, 8 KB = 8,192 bytes.

- All workloads set to 4 KB alignment.

- Data compressibility values of 0% and 20% as set with VDBench.

- All metrics represent sustained values, across full LBA range.

- Performance measured with queue depth set to 32.

- Drive write cache enabled. Due to the PLDP feature, the SSD always behaves as if WCE is enabled.

- Performance test precondition: Drive is preconditioned with 2x drive capacity 128 KB write IOs.

- Results obtained with a direct SATA port connection to host. Results may vary with system configuration.

2.3   Power

The drive uses either 5 V or it uses 5 and 12 V DC power.

Table 6   Power

	240 GB	480 GB	960 GB	1920 GB	3840 GB
Power					
Voltage (V)	5	5	5 / 12	5 / 12	5 / 12
Power Consumption					
Overall average active power (W)	2.3	2.7	3.2	3.4	3.5
Maximum average active power (W)	2.6	3.2	4.5	5.1	5.0
Peak (25uS sample) burst active power (W) 5V limited to 6W	4.9	5.4	7.8	8.8	8.6
Idle (W)	1.1	1.1	1.2	1.2	1.2

NOTE   5V power limited to 6 W beyond which power will be drawn from 12 V.

2.4   Environmental Conditions

Table 7   Temperature, Humidity, Shock

Specification	Values
Temperature	■ Operating: 0°C to 70°C ■ Non-operating: -40°C to 85°C
Humidity	■ Operating and Non-Operating: 5% - 95%
Shock	■ Operating: 1000G, duration 0.5ms ■ Non-Operating: 1000G, duration 0.5ms
Thermal gradient	■ Operating: 20°C/hour ■ Non-operating: 30°C/hour

NOTE   Operating, as measured by temperature sensor, SMART Attribute ID 194.

- Measured without condensation.

- The Shock specification assumes that the SSD is mounted securely with the input vibration applied to the drive mounting. Stimulus may be applied in the X, Y or Z axis.

- Operating Shock: The drive, as installed for normal operation, operates error-free while subjected to intermittent shock not exceeding specification. Shock may be applied in the X, Y, or Z-axis. Shock must not be repeated more than once every 2 seconds.

- Non-Operating Shock: The limits of non-operating shock applies to all conditions of handling and transportation. This includes isolated and integrated drives. Shock may be applied in the X, Y, or Z-axis.

Table 8   Vibration

Specification	Values
Maximum Vibrations	■ Operating: Random, 3.8 Grms, 10-3000Hz, Uniform PSD:0.005 G^2/Hz ■ Non-Operating: Random, 7 Grms, 10-500Hz, Uniform PSD:0.01 G^2/Hz

NOTE   The Vibration specification assumes that the SSD is mounted securely with the input Vibration applied to the drive mounting screws. Stimulus may be applied in the X, Y or Z axis.

- Operating Vibration: The drive, as installed for normal operation, shall operate error free while subjected to specified vibration not exceeding specification. Vibration may be applied in the X, Y, or Z-axis.

- Non-Operating Vibration: The limits of non-operating vibration shall apply to all conditions of handling and transportation. This includes both isolated drive and integrated drives. Vibration may be applied in the X, Y, or Z-axis.

2.5   Reliability

Table 9   Reliability

Specification	Values
Mean time between failures (MTBF)	2 million hours @ 55°C
Uncorrectable Bit Error Rate	<1 error in 10^{17} bits read

NOTE   The SSD achieves the specified MTBF in an operational environment that complies with the operational temperature range specified in this manual. Operating temperatures are measured by the temperature sensor, SMART Attribute ID, Primary Temperature, provided in Table 16, "SMART Attributes," on page 25.

2.6   Tunable Capacity

You can set the SSD to Capacity Optimized or Performance Optimized states. When shipped, the SSD is in the Capacity Optimized state. Use the Seagate utility, SeaTools^{TM} SSD to set the states. Seagate recommends to set the required state at deployment, prior to installing a file system. Changing states does not change the rated TWB specification for endurance.

2.7   Endurance

Table 10 Total Bytes Written

Specification	240 GB	480 GB	960 GB	1920 GB	3840 GB
Nytro 1351	435 TB	875 TB	1750 TB	3500 TB	7000 TB
Nytro 1551	1300 TB	2600 TB	5250 TB	10500 TB	21000 TB

NOTE   Information on endurance:

- TB=10^12 bytes

- DWPD is drive write per day.

- Limited Warranty with Media Usage provides coverage for the warranty period or the endurance usage of the drive, which ever comes first.

- Nytro 1551 endurance rating assumes that a typical enterprise data workload has 80% entropy. The SSD is fully warranted for enterprise workloads regardless of data entropy.

- SSD endurance is based on lifetime writes to the SSD from the host.

- Lifetime writes from host are available from the corresponding SMART attribute, see Table 16, *SMART Attributes, on page 25*.

3. Mechanical Information

## 3.1　　Dimensions and Weight

Weight: 77 g

Height: Maximum 7 mm

Width: 69.85±0.25

Length: 100±0.25

> **NOTE**　　　　All dimensions are in millimeters.

Figure 1 Dimensions
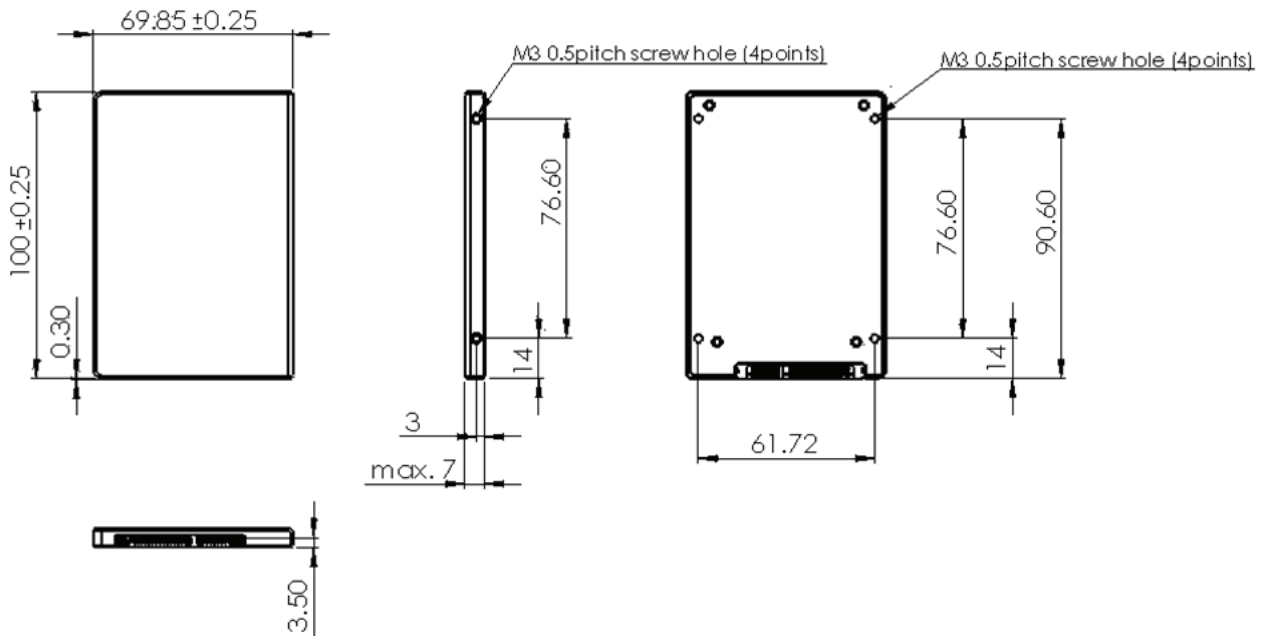
4. Pin and Signal Descriptions

4.1   Serial ATA Interface Connector

Figure 2 Connector Physical Dimension and Connector Assembly
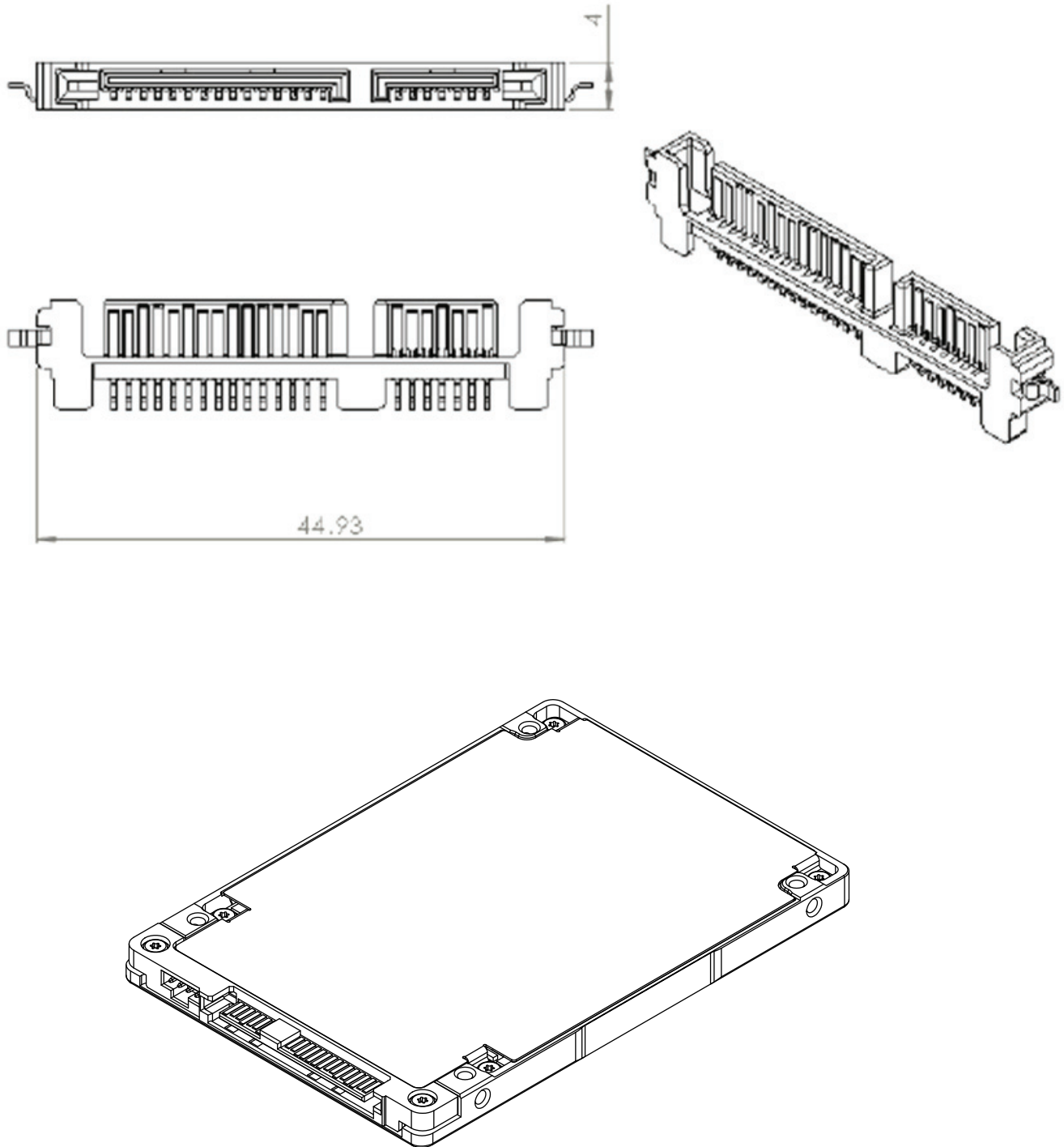
4.2　　　Pin Locations

Figure 3 Layout of 2.5-inch Signal and Power Segment Pins

Signal Pins　　　Power Pins
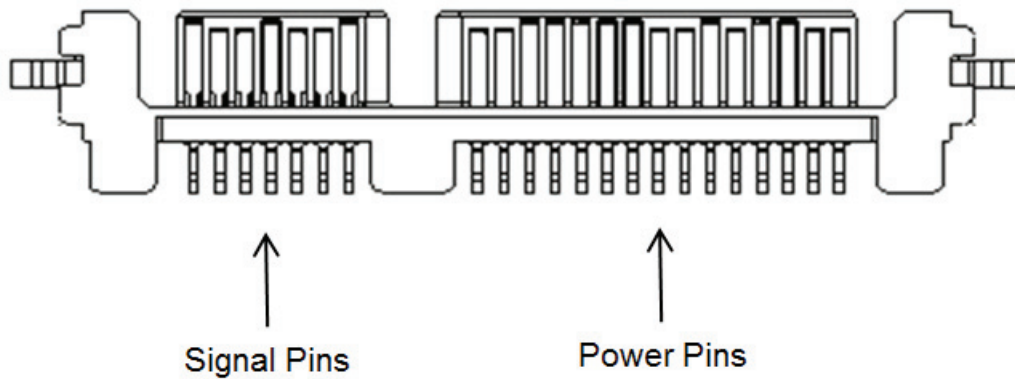
NOTE　　　　　The 2.5-inch connector supports built in latching capability.

4.3　　　Connector Pin Signal Definitions

Table 11 Serial ATA Connector Pin Signal Definitions—2.5-inch Form Factors

Pin	Name	Definition
S1	Ground	Ground
S2	A+	Differential signal pair +A and A-
S3	A-	
S4	Ground	Ground
S5	B-	Differential signal pair +B and B-
S6	B+	
S7	Ground	Ground

NOTE　　　　　Key and spacing separate the signal and power segments.

4.4   Power Pin Signal Definitions

Table 12 Serial ATA Power Pin Signal Definitions—2.5-inch Form Factors

Pin	Function	Definition
P1	V33	3.3 V Power; not used
P2	V33	3.3 V Power; not used
P3	V33	DevSlp; do not connect 3.3 V
P4	GND	Ground
P5	GND	Ground
P6	GND	Ground
P7	V5	5 V Power
P8	V5	5 V Power
P9	V5	5 V Power
P10	GND	Ground
P11	DAS	Device Activity Signal
P12	GND	Ground
P13	V12	12 V Power
P14	V12	12 V Power
P15	V12	12 V Power

NOTE   Key and spacing separate the signal and power segments.

- Uses 12 V and 5 V power only. The 240 GB and 480 GB models use 5 V supply only.

- Ground pins are P4, P5, P6, P10, and P12.

- P7, P8, and P9 are 5V power pins and are connected internally on the drive.

- P13, P14, and P15 are 12V power pins and are connected internally on the drive.

4.5   SSD Activity LED Indicator (Optional)

The SSD can support DAS Control function from the SSD module to indicate LED activity of host side.

The device includes a physical pin P11 for connecting device activity LEDs.

The signal provided to indicate activity of the device is a low-voltage and low-current driver. The signal from the device is not suitable for directly driving an LED and is first buffered using a circuit external to the device before driving an LED.

The DAS function firmware feature generates a Low and High toggle Activity signal on pin 11 when the SSD is in a busy state and generates a high Activity signal input when the SSD is in idle mode (Low level: GND, High level: 2.85 V).

The DAS Firmware feature is disabled and the R das is opened when the DAS function is not in use. See .

Figure 4 Circuit of SSD Activity LED indication
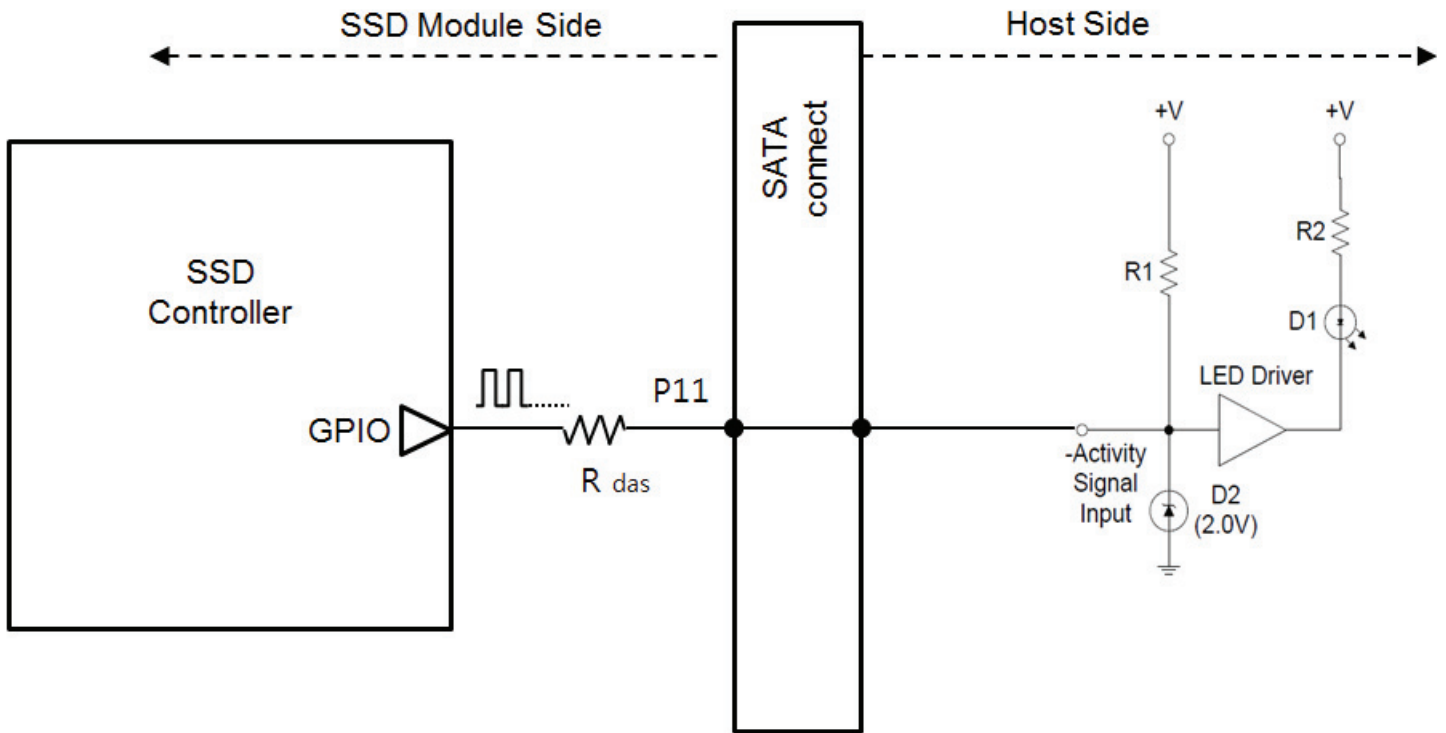
5. Supported ATA Command List

The SSD complies with ATA-8/ACS-4. All mandatory and many optional commands and features are supported.

5.1 ATA Feature Set

The following table shows the ATA feature set and commands that the SSD supports.

Table 13 ATA Feature Set

Feature
Power Management Command Set
Security Mode Feature Set
SMART Command Set
Device Statistics
SMART Command Transport
Dataset Management Command Set
Host Protected Area Command Set
48-bit Address Command Set
General Purpose Log Command Set
Native Command Queuing
Software Settings Prevention
ATA Sanitize Command Set
Identify Device Command Set

5.2   ATA Command Description

The following table shows the ATA commands supported.

Table 14 ATA Command Description

Command	Code (Hex)	Command	Code (Hex)
NOP	00h	EXECUTE DEVICE DIAGNOSTICS	90h
DATA SET MANAGEMENT	06h	DOWNLOAD MICROCODE	92h
REQUEST SENSE DATA EXT	0Bh	DOWNLOAD MICROCODE DMA	93h
READ SECTORS	20h	SMART	B0h
READ SECTORS EXT	24h	SANITIZE DEVICE	B4h
READ DMA EXT	25h	READ MULTIPLE	C4h
READ MULTIPLE EXT	29h	WRITE MULTIPLE	C5h
READ LOG EXT	2Fh	SET MULTIPLE MODE	C6h
WRITE SECTORS	30h	READ DMA	C8h
WRITE SECTORS EXT	34h	WRITE DMA	CAh
WRITE DMA EXT	35h	WRITE MULTIPLE FUA EXT	CEh
WRITE MULTIPLE EXT	39h	STANDBY IMMEDIATE	E0h
WRITE DMA FUA EXT	3Dh	IDLE IMMEDIATE	E1h
WRITE LOG EXT	3Fh	STANDBY	E2h
READ VERIFY SECTORS	40h	IDLE	E3h
READ VERIFY SECTORS EXT	42h	READ BUFFER	E4h
ZERO EXT	44h	CHECK POWER MODE	E5h
WRITE UNCORRECTABLE EXT	45h	SLEEP	E6h
READ LOG DMA EXT	47h	FLUSH CACHE	E7h
WRITE LOG DMA EXT	57h	WRITE BUFFER	E8h
TRUSTED NON-DATA	5Bh	READ BUFFER DMA	E9h
TRUSTED RECEIVE	5Ch	FLUSH CACHE EXT	EAh
TRUSTED RECEIVE DMA	5Dh	WRITE BUFFER DMA	EBh
TRUSTED SEND	5Eh	IDENTIFY DEVICE	ECh
TRUSTED SEND DMA	5Fh	SET FEATURES	EFh
READ FPDMA QUEUED	60h	SECURITY SET PASSWORD	F1h
WRITE FPDMA QUEUED	61h	SECURITY UNLOCK	F2h
NCQ QUEUE MANAGEMENT	63h	SECURITY ERASE PREPARE	F3h
SEND FPDMA QUEUED	64h	SECURITY ERASE UNIT	F4h
RECEIVE FPDMA QUEUED	65h	SECURITY FREEZE LOCK	F5h
SET DATE & TIME EXT	77h	SECURITY DISABLE PASSWORD	F6h
ACCESSIBLE MAX ADDRESS CONFIG	78h		

5.3   Security

The user/master password is supported.

When the device receives a normal SECURITY ERASE UNIT command, the device erases all data blocks including unallocated (hidden) blocks.

You can download firmware regardless of the security state.

Other security features:

- TCG- Enterprise and TCG-Opal support
- Crypto-erase sanitization
- Block-level sanitization
- Secure update of firmware

5.3.1   Password Loss

If you lose the user password, you can access the device using the master password. If both passwords are lost, there is no way to access the device. For TCG Opal SSDs, where the credentials are no longer known, PSID Revert can be used to regain the use of the SSD but all of the data on the drive will be erased.

6. SMART Support

6.1   SMART Command Set

The SSD supports the SMART Command Set shown in the following table.

Table 15 SMART Commands

Feature Field Values	Command
D0h	SMART READ DATA
D1h	SMART READ ATTRIBUTE THRESHOLDS
D2h	SMART ENABLE/DISABLE ATTRIBUTE AUTOSAVE
D3h	SAVE ATTRIBUTE VALUES
D4h	SMART EXECUTE OFF-LINE IMMEDIATE
00h*	Execute SMART Off-Line routine
01h*	Execute SMART Short Self-test routine (Off-Line)
02h*	Execute SMART Extended Self-test routine (Off-Line)
03h*	Execute SMART Conveyance self-test routine in off-line mode
04h*	Execute SMART Selective self-test routine in off-line mode
7Fh*	Abort Off-Line routine
81h*	Execute SMART Short Self-test routine (Captive)
82h*	Execute SMART Extended Self-test routine (Captive)
83h*	Execute SMART Conveyance self-test routine in captive mode
84h*	Execute SMART Selective self-test routine in captive mode
D5h	SMART READ LOG
D6h	SMART WRITE LOG
D8h	SMART ENABLE OPERATIONS
D9h	SMART DISABLE OPERATIONS
DAh	SMART RETURN STATUS
*Low LBA values	

6.2   SMART Attributes

The SSD supports the SMART attributes shown in the following table.

Table 16 SMART Attributes

Name	Default Assignment	Description	Units
Raw Read Error Rate	1	A normalized rate of moderate to severe latency causing correctable errors.	Percentage
Reallocated Sector Count	5	Count of the number of blocks that have been reallocated, excluding pending sectors.	Counter
Power-On-Hours	9	Count of the lifetime power on hours in the Active or Idle ATA state.	Hours
Power Cycle Count	12	Count of the number of complete power up cycles. Excludes power mode state changes with power continuously applied.	Counter
Flash GB Erased	100	Count in GB of the lifetime erases of flash for all purposes.	Count in Giga bytes (2^30)
Lifetime PS4 Entry Count	102	Count of the number of times the PS4 power state is entered.	Counter
Lifetime PS3 Entry Count	103	Count of the number of times the PS3 power state is entered.	Counter
Grown Bad Block Count	170	Count of the number of retired flash blocks post manufacturing.	Counter
Program Fail Count	171	Count of the number of Flash Program failures.	Counter
Erase Fail Count	172	Count of the number of Flash Erase failures.	Counter
Average Program/Erase Count	173	Count of the average number of program/erase cycles on all good blocks.	Counter
Unexpected Power Loss Count	174	Count of the number of complete power loss events not preceded by a shutdown command. Excludes power mode state changes with power continuously applied.	Counter
Wear Range Delta	177	Difference between the most and least worn blocks with regards to the maximum rated P-E cycles (most-least)/max*100.	Percentage
SATA/PCIe Interface Downshift Count	183	Count of the number of times SATA interface rate reduction is negotiated.	Counter
Uncorrectable ECC Count	187	Count of the number of unsuccessful ECC recovery attempts where higher level recovery methods also failed.	Counter
Primary Temperature	194	Current, lifetime maximum and lifetime minimum temperature.	Celsius (Signed data)
RAISE ECC Correctable Count	195	Count of the number of times RAISE successfully recovered data.	Counter
Uncorrectable Read Error Count	198	Count of the number of times an uncorrectable error is returned to the host on a read command.	Counter
SATA R-Error (CRC) Error Count	199	Count of the number of detected SATA R-Errors experienced on the SATA receiver.	Counter
Drive Life Protection Status	230	Power fail protection available.	100d, 64h unprotected SSD RO, 90d, 5Ah protected

Table 16 SMART Attributes

Name	Default Assignment	Description	Units
SSD Life Left	231	Approximate percent SSD life left, in terms of program/erase cycles or Flash blocks currently available for use.	Percentage
Available Reserved Space	232	Ratio of currently available internal reserved space to as built reserved space.	Percentage
Lifetime Writes to Flash	233	Sum in GB of the lifetime writes to flash for all purposes.	Sum in Giga bytes (2^{30})
Lifetime Writes from Host	241	Sum in GB of the lifetime writes for all host write commands.	Sum in Giga bytes (2^{30})
Lifetime Reads from Host	242	Sum in GB of the lifetime reads for all host read commands.	Sum in Giga bytes (2^{30})
Free Space	243	Available user capacity in MB and percent of currently set user capacity.	Percentage User MB Free and percentage user space remaining

6.3   SMART Trip

SMART trip (threshold exceeded condition) indicates impending degradation or fault condition. The host can issue a SMART return status command (B0h/DAh) to communicate the reliability status of the drive. The threshold-exceeded condition is also checked during drive self tests.

7. Standards and Reference Documents

Each Hard Drive and Solid State Drive ("device") has a product label that includes certifications that are applicable to that specific drive. The following information provides an overview of requirements that may be applicable to the drive.

7.1   Regulatory Model Numbers

The following regulatory model number represents all features and configurations within the series:

- STA010

7.2   Agency and Safety Certifications

7.2.1   Safety Certification

These products are certified to meet the requirements of UL/cUL 60950-1, EN 60950-1, and may also include, IEC 62368, UL 62368 and EN 62368.

7.2.2   Electromagnetic Compatibility

The device, as delivered, is designed for system integration and installation into a suitable enclosure prior to use. The drive is supplied as a subassembly and is not subject to Subpart B of Part 15 of the FCC Rules.

The design characteristics of the drive serve to minimize radiation when installed in an enclosure that provides reasonable shielding. The device is capable of meeting the Class B limits of the FCC Rules and Regulations of the Canadian Department of Communications when properly packaged; however, it is the user's responsibility to assure that the device meets the appropriate EMI requirements in their system.

7.2.3   Electromagnetic Susceptibility

The device as delivered is tested to meet susceptibility requirements in a representative enclosure. It is the responsibility of those integrating the drive within their systems to perform those tests required and design their system to ensure that equipment operating in the same system as the drive or external to the system does not adversely affect the performance of the device.

7.2.4   Electromagnetic Compliance

Seagate uses an independent laboratory to confirm compliance with the EMC directives and standards. The device was tested in a representative system for typical applications.Although the test system with this Seagate model complies with the directives/standards, we cannot guarantee that all systems will comply. The computer manufacturer or system integrator shall confirm EMC compliance and provide the appropriate marking for their product.

7.2.5   European Union (EU) CE Marking Requirements

Devices that display the CE mark comply with the European Union (EU) requirements specified in the Electromagnetic Compatibility Directive (2014/30/EU). Testing is performed to the levels specified by the product standards for Information Technology Equipment (ITE). Emission levels are defined by EN 55032:2012, Class B and the immunity levels are defined by EN 55024.

The devices also meet the requirements of The Low Voltage Directive (LVD) 2014/35/EU.

Although CE-marked Seagate devices comply with all relevant regulatory requirements and standards for the drives, Seagate cannot guarantee that all system-level products into which the devices are installed comply with all regulatory requirements and standards applicable to the system-level products. The device is designed for operation inside a properly designed system (e.g., enclosure designed for the device), with properly shielded I/O cable (if necessary) and terminators on all unused I/O ports. Computer manufacturers and system integrators should confirm EMC compliance and provide CE marking for the system-level products.

For compliance with the RoHS "Recast" Directive 2011/65/EU (RoHS 2), .

7.2.6   Australian and New Zealand RCM Compliance Mark

If the device has the RCM marking, it complies with the Australia/New Zealand Standard AS/NZ CISPR32 and meets the Electromagnetic Compatibility (EMC) Framework requirements of the Australian Communications and Media Authority (ACMA).

7.2.7   Canada ICES-003

If the device has the ICES-003 Issue 6 marking, it complies with the requirements of ICES tested per ANSI C63.4-2014 or CAN/CSA-CISPR 22-10.

7.2.8   South Korean Certification Mark

If the device has the Korean Communications Commission (KCC) logo, they comply with KN32 and KN35.

기 종 별	사 용 자 안 내 문
B급 기기 (가정용 방송통신기자재)	이 기기는 가정용(B급) 전자파적합기기로서 주로 가정에서 사용하는 것을 목적으로 하며, 모든 지역에서 사용할 수 있습니다.

7.2.9   Morocco Commodity Mark

Seagate drives are tested for compliance and comply with the European Union (EU) Electromagnetic Compatibility (EMC) Directive 2014/30/EU and the Low Voltage Directive (LVD) 2014/35/EU. Accordingly, the drives also meet the requirements of Morocco's Order of the Minister of Industry, Trade, Investment and Digital Economy No. 2574-14 of 29 Ramadan 1436 (16 July 2015) on electromagnetic compatibility of equipment.

For devices with the Morocco Mark, Seagate has added the Moroccan Commodity Mark to the devices provided to the OEM for the sale of Customer Kits produced by our OEM customers that are intended to be incorporated into the OEM's finished system-level product by an end user. The Customer Kits are considered 'devices' under Morocco's Order of the Minister of Industry, Trade, Investment and Digital Economy No. 2574-14 of 29 Ramadan 1436 (16 July 2015) on electromagnetic compatibility of equipment.

7.2.10   Taiwanese BSMI

Devices with the Taiwanese certification mark comply with Chinese National Standard, CNS13438 (2006.6) and CNS 15663 (2013.7).

For compliance with the Taiwan Bureau of Standards, Metrology and Inspection's (BSMI) RoHS requirements,

7.3   Environmental Protection

Seagate designs its products to meet environmental protection requirements worldwide, including regulations restricting certain chemical substances.

7.3.1   European Union Restriction of Hazardous Substance Law

7.3.1.1   Restriction of Hazardous Substances in Electrical and Electronic Equipment

Seagate devices are designed to be compliant with the European Union RoHS "Recast" Directive 2011/65/EU (RoHS 2) as amended by Directive (EU) 2015/863. The RoHS2 restricts the use of certain hazardous substances such as Lead, Cadmium, Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB) and Polybrominated Diphenyl Ether (PBDE), BisBis(2-Ethylhexyl) phthalate (DEHP), Benzyl butyl phthalate (BBP), Dibutyl phthalate (DBP), and Diisobutyl phthalate (DIBP) in electrical and electronic equipment (EEE).

7.3.1.2   Substances of Very High Concern (SVHC)

The European Union REACH (Registration, Evaluation, Authorization and Restriction of Chemicals) Regulation (EC) 1907/2006 regulates chemicals shipped into and used in Europe. A number of parts and materials in Seagate products are procured from external suppliers. We rely on the representations of our suppliers regarding the presence of REACH substances in these articles and materials. Our supplier contracts require compliance with our chemical substance restrictions, and our suppliers document their compliance with our requirements by providing full-disclosure material content declarations that disclose inclusion of any REACH-regulated substance in such articles or materials. Product-specific REACH declarations are available upon request through your Seagate Sales Representative.

7.3.2   China Requirements —China RoHS 2

China RoHS 2 refers to the Ministry of Industry and Information Technology Order No. 32, effective July 1, 2016, titled Management Methods for the Restriction of the Use of Hazardous Substances in Electrical and Electronic Products. To comply with China RoHS 2, Seagate determined this product's Environmental Protection Use Period (EPUP) to be 20 years in accordance with the *Marking for the Restricted Use of Hazardous Substances in Electronic and Electrical Products,* SJT 11364-2014.

Table 17 China - Hazardous Substances

部件名称 Part Name	有害物质 Hazardous Substances					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr^{+6})	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
印刷电路板组装 PCBA	X	O	O	O	O	O
机壳 Chassis	X	O	O	O	O	O
本表格依据 SJ/T 11364 的规定编制。 This table is prepared in accordance with the provisions of SJ/T 11364-2014 O：表示该有害物质在该部件所有均质材料中的含量均在 GB/T 26572 规定的限量要求以下。 O：Indicates that the hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement of GB/T26572. X：表示该有害物质至少在该部件的某一均质材料中的含量超出 GB/T 26572 规定的限量要求。 X：Indicates that the hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement of GB/T26572.						

7.3.3   Taiwan Requirements — Taiwan RoHS

Taiwan RoHS refers to the Taiwan Bureau of Standards, Metrology and Inspection's (BSMI) requirements in standard CNS 15663, Guidance to reduction of the restricted chemical substances in electrical and electronic equipment. Seagate products must comply with the "Marking of presence" requirements in Section 5 of CNS 15663, effective January 1, 2018. This product is Taiwan RoHS compliant.

The following table meets the Section 5 "Marking of presence" requirements.

Table 18 Taiwan - Restricted Substances

設備名稱：固態硬碟， Equipment Name: 2.5 inch SSDs				型號（型式） Type Designation (Type)		
單元 Unit	限用物質及其化學符號 Restricted Substance and its chemical symbol					
	鉛 Lead (Pb)	汞 Mercury (Hg)	鎘 Cadmium (Cd)	六價鉻 Hexavalent Chromium (Cr^{+6})	多溴聯苯 Polybrominated biphenyls (PBB)	多溴二苯醚 Polybrominated diphenyl ethers (PBDE)
快閃記憶體 Flash Memory	O	O	O	O	O	O
連接器 Connector	O	O	O	O	O	O
外殼 Product Cover	O	O	O	O	O	O
印刷電路板總成 PCB Assembly	—	O	O	O	O	O
備考1.〝超出0.1 wt %〞及〝超出0.01 wt %〞係指限用物質之百分比含量超出百分比含量基準值。 Note 1: "Exceeding 0.1 wt %" and "exceeding 0.01 wt %" indicate that the percentage content of the restricted substance exceeds the reference percentage value of presence condition.						
備考2.〝O〞係指該項限用物質之百分比含量未超出百分比含量基準值。 Note 2. "O" indicates that the percentage content of the restricted substance does not exceed the percentage of reference value of presence.						
備考3.〝—〞係指該項限用物質為排除項目。 Note 3. "—" indicates that the restricted substance corresponds to the exemption.						

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